

TEXAS INSTRUMENTS Bill of Materials TI DESIGNS TIDA-00266 DRV2605EVM-BT

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	2	C1, C2	0.1uF	CAP, CERM, 0.1uF, 16V, +/-10%, X7R,	MuRata	GRM155R71C104KA88D		0402	
				CAP, CERM, 1uF, 10V, +/-10%, X5R,					
2	2	C3, C17	1uF	0402	MuRata	GRM155R61A105KE15D		0402	
				CAP, CERM, 4.7uF, 6.3V, +/-20%, X5R,					
3	1	C4	4.7uF	0402	TDK	C1005X5R0J475M050BC		0402	
				CAP, CERM, 0.1uF, 10V, +/-10%, X7R,					
4	2	C5, C8	0.1uF	0402	MuRata	GRM155R71A104KA01D		0402	
		,		CAP. CERM. 0.01uF. 25V. +/-10%.					
5	1	C6	0.01uF	X7R. 0402	MuRata	GRM155R71E103KA01D		0402	
		Co	0.0101	CAP, CERM, 2200pF, 50V, +/-10%,	Ividitata	GINVIDSIO/ILIOSIOAOID		0402	
6	1	C7	2200pF	X7R. 0402	MuRata	GRM155R71H222KA01D		0402	
0	1	C7	2200pr	CAP, CERM, 10uF, 10V, +/-20%, X5R,	iviunata	GRIVITJ3R7111222RAUID		0402	
7	2	CO C40	405		TDK	CACOOVEDAAAOCAA		0000	
	2	C9, C10	10uF	0603	IDK	C1608X5R1A106M		0603	
				CAP, CERM, 0.1uF, 50V, +/-10%,					
8	1	C11	0.1uF	COG/NP0, 0402	TDK	C1005X7R1H104K		0402	
				CAP, CERM, 22pF, 50V, +/-5%,					
9	2	C13, C14	22pF	COG/NP0, 0402	MuRata	GRM1555C1H220JA01D		0402	
				CAP, CERM, 4.7uF, 10V, +/-20%, X5R,					
10	2	C15, C16	4.7uF	0402	MuRata	GRM155R61A475M		0402	
				CAP, CERM, 1000pF, 25V, +/-5%,					
11	1	C18	1000pF	COG/NP0, 0402	TDK	C1005C0G1E102J		0402	
				CAP, CERM, 47uF, 6.3V, +/-20%, X5R,					
12	1	C19	47uF	0603	MuRata	GRM188R60J476M		0603	
		D1, D2, D3, D4, D5, D6, D7, D8,							
13	12	D9, D10, D11, D12		LED. White, SMD	Rohm	SML312WBCW1		LED, 0603	
14	1	D13	Orange	LED, Orange, SMD	Rohm	SML-P12DTT86		Orange LED	
15	1	D14	Yellow	LED, Yellow, SMD	Rohm	SML-P12YTT86		Yellow LED	
16	1	H1	TEHOW	USB A MALE TO MICRO B MALE 6'	Qualtek	3025013-06		Used in PnP output	
16	1	HT.		USB A WALE TO WICKO B WALE 6		3023013-00		Osed III PIIP Output	
					Samsung Electro-				
17	1	H3		SEMCO1030 LRA Actuator	Mechanics	DMJBRN1030		Used in PnP output	
				3 X AAA BATTERY HOLDER WITH					
18	1	H4		ON/OFF SWITCH AND 2-PIN JST	Adafruit	727		Used in PnP output	
				Connector, micro USB Type B,					
19	1	J2		Receptacle, R/A, SMD	Hirose Electric Co. Ltd.	ZX62-B-5PA(11)		Micro USB-B receptacle	
20	1	J3		Header, 2x1,2mm, R/A, SMT	JST Manufacturing	S2B-PH-SM4-TB(LF)(SN)		Header, 2x1, 2mm, R/A	
21	1	L1	1uH	Inductor, Multilayer, Ferrite, 1uH,	MuRata	LQM21PN1R0MC0D		0805	
22	4	R1, R8, R12, R33	10.0k	RES, 10.0k ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW040210K0FKED		0402	
23	11	R2, R7, R11, R18, R19, R20,	0	RES, 0 ohm, 5%, 0.063W, 0402	Vishay-Dale	CRCW04020000Z0ED		0402	
24	2	R9, R34	1.50k	RES, 1.50k ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW04021K50FKED		0402	
25	12	R10, R22, R23, R24, R25, R26,	75.0	RES, 75.0 ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW040275R0FKED		0402	
26	1	R13	7.32k	RES, 7.32k ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW04027K32FKED		0402	
27	1	R16	14.7k	RES, 14.7k ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW040214K7FKED		0402	
28	1	R17	8.66k	RES, 8.66k ohm, 1%, 0.063W, 0402	Vishay-Dale	CRCW04028K66FKED		0402	
29	1	S1		12V, SMT	C&K Components	PTS840 PM SMTR LFS		3.5x1.35x3.55mm	
30	1	S2	OTD	Switch, Slide, SPDT, 0.3A, SMT	E-Switch	EG1257		6.7x1.4x2.6mm	
31	2	TP1, TP2	STD	PAD, 5X5mm	STD	STD			
				Haptic Driver for ERM and LRA with	1				
22	1	U1		Built-In Library and Smart Loop Architecture, YZF0009ADAD	Texas Instruments	DRV2605YZF		YZF0009ADAD	
32	-	01		BLUETOOTH SMART (BLE)	rexas iristruments	DKVZ0031ZF		TZFUUU9ADAD	
33	1	U2		MODULE	LS RESEARCH	TiWi-uB1		17.9x2.2x11.6mm	
33	1	U3		Dynamic Power Management, 10.5 V	Texas Instruments	BQ24232RGTR		RGT0016C	
34 35	1	U4		WITH 1A SWITCHES AND	Texas Instruments	TPS63051YFF		YFF0012AFAF	
36	1	X2		Crystal, 32.768kHz, 12.5pF, SMD	NDK	MUS-2		2-SMD	
		// <u>/</u>	0	RES, 0 ohm, 5%, 0.063W, 0402	Vishay-Dale	CRCW04020000Z0ED		2-SWD 0402	

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